

Die Attach Machine Market Report by Type (Flip Chip Bonder, Die Bonder), Technique (Epoxy, Soft Solder, Sintering, Eutectic, and Others), Application (RF and MEMS, Optoelectronics, Logic, Memory, CMOS Image Sensors, LED, and Others), and Region 2024-2032

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Abstracts

The global die attach machine market size reached US\$ 1,121.1 Million in 2023. Looking forward, IMARC Group expects the market to reach US\$ 1,678.9 Million by 2032, exhibiting a growth rate (CAGR) of 4.4% during 2024-2032. The increasing production of semiconductors, rising demand for renewable energy sources and the growing sales of autonomous, electric, and luxury vehicles represent some of the key factors driving the market.

Die attach is the process wherein a semiconductor chip is attached to a substrate or package. It is considered fundamental to different types of packaging and uses various materials, such as epoxy, polyimide, and silver-filled glass. It is operated using a die attach machine that is designed to handle and place the die onto the substrate or package with high accuracy and precision. A die attach machine, also known as a die mount or die bond machine, is equipped with vision systems and other sensors to ensure that the die is adequately positioned and bonded using a heated adhesive or a thermocompression bonding process. At present, rising sales of consumer electronic devices are catalyzing the demand for die attach machine across the globe.

Die Attach Machine Market Trends:

The increasing utilization of die attach machines in the production of semiconductor devices, such as microprocessors, memory chips, and other integrated circuits (ICs), represents one of the major factors strengthening the market growth around the world. Moreover, the rising use of die attach machines in the packaging of semiconductor

devices is favoring the market growth. In addition, the growing usage of die attach machines in the manufacturing of printed circuit boards (PCBs) to connect electronic components in different electronic devices is influencing the market positively. Apart from this, die attach machines are employed in the automotive industry to manufacture various parts of vehicles, including sensors, engine and transmission control modules, safety, navigation, and audio systems, advanced driver assistance systems (ADAS), and electric motor controllers. This, coupled with the increasing sales of electric and luxury vehicles on account of inflating income levels, is contributing to the market growth. Furthermore, there is a rise in the adoption of die attach machines in medical devices like pacemakers, insulin pumps, implantable devices, glucose meters, and blood pressure monitors. This, along with the surging prevalence of severe medical conditions, is fueling the market growth. Additionally, the increasing demand for wearable devices, such as smartwatches and fitness trackers, is creating a positive outlook for the market. Besides this, the growing demand for renewable energy sources, such as wind turbines and solar panels, is driving the need for die attach machines.

Key Market Segmentation:

IMARC Group provides an analysis of the key trends in each segment of the global die attach machine market, along with forecasts at the global, regional, and country level from 2024-2032. Our report has categorized the market based on type, technique, and application.

Type Insights:

Flip Chip Bonder
Die Bonder

The report has provided a detailed breakup and analysis of the die attach machine market based on the type. This includes flip chip bonder and die bonder. According to the report, die bonder represented the largest segment.

Technique Insights:

Epoxy
Soft Solder
Sintering
Eutectic
Others

A detailed breakup and analysis of the die attach machine market based on the technique has also been provided in the report. This includes epoxy, soft solder, sintering, eutectic, and others. According to the report, epoxy represented the largest segment.

Application Insights:

- RF and MEMS
- Optoelectronics
- Logic
- Memory
- CMOS Image Sensors
- LED
- Others

The report has provided a detailed breakup and analysis of the die attach machine market based on the application. This includes RF and MEMS, optoelectronics, logic, memory, CMOS image sensors, LED, and others. According to the report, LED represented the largest segment.

Regional Insights:

- North America
 - United States
 - Canada
- Asia-Pacific
 - China
 - Japan
 - India
 - South Korea
 - Australia
 - Indonesia
 - Others
- Europe
 - Germany
 - France
 - United Kingdom
 - Italy
 - Spain

Russia
Others
Latin America
Brazil
Mexico
Others
Middle East and Africa

The report has also provided a comprehensive analysis of all the major regional markets, which include North America (the United States and Canada); Asia Pacific (China, Japan, India, South Korea, Australia, Indonesia, and others); Europe (Germany, France, the United Kingdom, Italy, Spain, Russia, and others); Latin America (Brazil, Mexico, and others); and the Middle East and Africa. According to the report, Asia Pacific was the largest market for die attach machines. Some of the factors driving the Asia Pacific die attach machine market included the increasing demand for semiconductor devices, advancements in packaging technology, and rising adoption of automation in the semiconductor industry.

Competitive Landscape:

The report has also provided a comprehensive analysis of the competitive landscape in the global die attach machine market. Competitive analysis such as market structure, market share by key players, player positioning, top winning strategies, competitive dashboard, and company evaluation quadrant has been covered in the report. Also, detailed profiles of all major companies have been provided. Some of the companies covered Anza Technology Inc., ASM Pacific Technology Limited, Be Semiconductor Industries N.V., Dr. Tresky AG, Fasford Technology Co Ltd. (Fuji Machinery Co., Ltd), Hybond Inc., Inseto UK Limited, Kulicke and Soffa Industries Inc., MicroAssembly Technologies Ltd., MRSI Systems (Mycronic AB (Publ)), Palomar Technologies Inc., Shinkawa Ltd. (Yamaha Motor Co. Ltd.), etc. Kindly note that this only represents a partial list of companies, and the complete list has been provided in the report.

Key Questions Answered in This Report:

How has the global die attach machine market performed so far, and how will it perform in the coming years?

What are the drivers, restraints, and opportunities in the global die attach machine market?

What is the impact of each driver, restraint, and opportunity on the global die attach machine market?

What are the key regional markets?

- Which countries represent the most attractive die attach machine markets?
- What is the breakup of the market based on the type?
- Which is the most attractive type in the die attach machine market?
- What is the breakup of the market based on the technique?
- Which is the most attractive technique in the die attach machine market?
- What is the breakup of the market based on the application?
- Which is the most attractive application in the die attach machine market?
- What is the competitive structure of the global die attach machine market?
- Who are the key players/companies in the global die attach machine market?

Contents

1 PREFACE

2 SCOPE AND METHODOLOGY

- 2.1 Objectives of the Study
- 2.2 Stakeholders
- 2.3 Data Sources
 - 2.3.1 Primary Sources
 - 2.3.2 Secondary Sources
- 2.4 Market Estimation
 - 2.4.1 Bottom-Up Approach
 - 2.4.2 Top-Down Approach
- 2.5 Forecasting Methodology

3 EXECUTIVE SUMMARY

4 INTRODUCTION

- 4.1 Overview
- 4.2 Key Industry Trends

5 GLOBAL DIE ATTACH MACHINE MARKET

- 5.1 Market Overview
- 5.2 Market Performance
- 5.3 Impact of COVID-19
- 5.4 Market Forecast

6 MARKET BREAKUP BY TYPE

- 6.1 Flip Chip Bonder
 - 6.1.1 Market Trends
 - 6.1.2 Market Forecast
- 6.2 Die Bonder
 - 6.2.1 Market Trends
 - 6.2.2 Market Forecast

7 MARKET BREAKUP BY TECHNIQUE

7.1 Epoxy

7.1.1 Market Trends

7.1.2 Market Forecast

7.2 Soft Solder

7.2.1 Market Trends

7.2.2 Market Forecast

7.3 Sintering

7.3.1 Market Trends

7.3.2 Market Forecast

7.4 Eutectic

7.4.1 Market Trends

7.4.2 Market Forecast

7.5 Others

7.5.1 Market Trends

7.5.2 Market Forecast

8 MARKET BREAKUP BY APPLICATION

8.1 RF and MEMS

8.1.1 Market Trends

8.1.2 Market Forecast

8.2 Optoelectronics

8.2.1 Market Trends

8.2.2 Market Forecast

8.3 Logic

8.3.1 Market Trends

8.3.2 Market Forecast

8.4 Memory

8.4.1 Market Trends

8.4.2 Market Forecast

8.5 CMOS Image Sensors

8.5.1 Market Trends

8.5.2 Market Forecast

8.6 LED

8.6.1 Market Trends

8.6.2 Market Forecast

8.7 Others

8.7.1 Market Trends

8.7.2 Market Forecast

9 MARKET BREAKUP BY REGION

9.1 North America

9.1.1 United States

9.1.1.1 Market Trends

9.1.1.2 Market Forecast

9.1.2 Canada

9.1.2.1 Market Trends

9.1.2.2 Market Forecast

9.2 Asia-Pacific

9.2.1 China

9.2.1.1 Market Trends

9.2.1.2 Market Forecast

9.2.2 Japan

9.2.2.1 Market Trends

9.2.2.2 Market Forecast

9.2.3 India

9.2.3.1 Market Trends

9.2.3.2 Market Forecast

9.2.4 South Korea

9.2.4.1 Market Trends

9.2.4.2 Market Forecast

9.2.5 Australia

9.2.5.1 Market Trends

9.2.5.2 Market Forecast

9.2.6 Indonesia

9.2.6.1 Market Trends

9.2.6.2 Market Forecast

9.2.7 Others

9.2.7.1 Market Trends

9.2.7.2 Market Forecast

9.3 Europe

9.3.1 Germany

9.3.1.1 Market Trends

9.3.1.2 Market Forecast

9.3.2 France

- 9.3.2.1 Market Trends
- 9.3.2.2 Market Forecast
- 9.3.3 United Kingdom
 - 9.3.3.1 Market Trends
 - 9.3.3.2 Market Forecast
- 9.3.4 Italy
 - 9.3.4.1 Market Trends
 - 9.3.4.2 Market Forecast
- 9.3.5 Spain
 - 9.3.5.1 Market Trends
 - 9.3.5.2 Market Forecast
- 9.3.6 Russia
 - 9.3.6.1 Market Trends
 - 9.3.6.2 Market Forecast
- 9.3.7 Others
 - 9.3.7.1 Market Trends
 - 9.3.7.2 Market Forecast
- 9.4 Latin America
 - 9.4.1 Brazil
 - 9.4.1.1 Market Trends
 - 9.4.1.2 Market Forecast
 - 9.4.2 Mexico
 - 9.4.2.1 Market Trends
 - 9.4.2.2 Market Forecast
 - 9.4.3 Others
 - 9.4.3.1 Market Trends
 - 9.4.3.2 Market Forecast
- 9.5 Middle East and Africa
 - 9.5.1 Market Trends
 - 9.5.2 Market Breakup by Country
 - 9.5.3 Market Forecast

10 DRIVERS, RESTRAINTS, AND OPPORTUNITIES

- 10.1 Overview
- 10.2 Drivers
- 10.3 Restraints
- 10.4 Opportunities

11 VALUE CHAIN ANALYSIS

12 PORTERS FIVE FORCES ANALYSIS

- 12.1 Overview
- 12.2 Bargaining Power of Buyers
- 12.3 Bargaining Power of Suppliers
- 12.4 Degree of Competition
- 12.5 Threat of New Entrants
- 12.6 Threat of Substitutes

13 PRICE ANALYSIS

14 COMPETITIVE LANDSCAPE

- 14.1 Market Structure
- 14.2 Key Players
- 14.3 Profiles of Key Players
 - 14.3.1 Anza Technology Inc.
 - 14.3.1.1 Company Overview
 - 14.3.1.2 Product Portfolio
 - 14.3.2 ASM Pacific Technology Limited
 - 14.3.2.1 Company Overview
 - 14.3.2.2 Product Portfolio
 - 14.3.3 Be Semiconductor Industries N.V.
 - 14.3.3.1 Company Overview
 - 14.3.3.2 Product Portfolio
 - 14.3.3.3 Financials
 - 14.3.3.4 SWOT Analysis
 - 14.3.4 Dr. Tresky AG
 - 14.3.4.1 Company Overview
 - 14.3.4.2 Product Portfolio
 - 14.3.5 Fasford Technology Co Ltd. (Fuji Machinery Co., Ltd)
 - 14.3.5.1 Company Overview
 - 14.3.5.2 Product Portfolio
 - 14.3.6 Hybond Inc.
 - 14.3.6.1 Company Overview
 - 14.3.6.2 Product Portfolio
 - 14.3.7 Inseto UK Limited

- 14.3.7.1 Company Overview
- 14.3.7.2 Product Portfolio
- 14.3.8 Kulicke and Soffa Industries Inc.
 - 14.3.8.1 Company Overview
 - 14.3.8.2 Product Portfolio
 - 14.3.8.3 Financials
- 14.3.9 MicroAssembly Technologies Ltd.
 - 14.3.9.1 Company Overview
 - 14.3.9.2 Product Portfolio
- 14.3.10 MRSI Systems (Mycronic AB (Publ))
 - 14.3.10.1 Company Overview
 - 14.3.10.2 Product Portfolio
- 14.3.11 Palomar Technologies Inc.
 - 14.3.11.1 Company Overview
 - 14.3.11.2 Product Portfolio
- 14.3.12 Shinkawa Ltd. (Yamaha Motor Co. Ltd.)
 - 14.3.12.1 Company Overview
 - 14.3.12.2 Product Portfolio

Kindly note that this only represents a partial list of companies, and the complete list has been provided in the report.

List Of Tables

LIST OF TABLES

Table 1: Global: Die Attach Machine Market: Key Industry Highlights, 2023 & 2032

Table 2: Global: Die Attach Machine Market Forecast: Breakup by Type (in Million US\$), 2024-2032

Table 3: Global: Die Attach Machine Market Forecast: Breakup by Technique (in Million US\$), 2024-2032

Table 4: Global: Die Attach Machine Market Forecast: Breakup by Application (in Million US\$), 2024-2032

Table 5: Global: Die Attach Machine Market Forecast: Breakup by Region (in Million US\$), 2024-2032

Table 6: Global: Die Attach Machine Market: Competitive Structure

Table 7: Global: Die Attach Machine Market: Key Players

List Of Figures

LIST OF FIGURES

Figure 1: Global: Die Attach Machine Market: Major Drivers and Challenges

Figure 2: Global: Die Attach Machine Market: Sales Value (in Million US\$), 2018-2023

Figure 3: Global: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 4: Global: Die Attach Machine Market: Breakup by Type (in %), 2023

Figure 5: Global: Die Attach Machine Market: Breakup by Technique (in %), 2023

Figure 6: Global: Die Attach Machine Market: Breakup by Application (in %), 2023

Figure 7: Global: Die Attach Machine Market: Breakup by Region (in %), 2023

Figure 8: Global: Die Attach Machine (Flip Chip Bonder) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 9: Global: Die Attach Machine (Flip Chip Bonder) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 10: Global: Die Attach Machine (Die Bonder) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 11: Global: Die Attach Machine (Die Bonder) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 12: Global: Die Attach Machine (Epoxy) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 13: Global: Die Attach Machine (Epoxy) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 14: Global: Die Attach Machine (Soft Solder) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 15: Global: Die Attach Machine (Soft Solder) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 16: Global: Die Attach Machine (Sintering) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 17: Global: Die Attach Machine (Sintering) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 18: Global: Die Attach Machine (Eutectic) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 19: Global: Die Attach Machine (Eutectic) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 20: Global: Die Attach Machine (Other Techniques) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 21: Global: Die Attach Machine (Other Techniques) Market Forecast: Sales

Value (in Million US\$), 2024-2032

Figure 22: Global: Die Attach Machine (RF and MEMS) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 23: Global: Die Attach Machine (RF and MEMS) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 24: Global: Die Attach Machine (Optoelectronics) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 25: Global: Die Attach Machine (Optoelectronics) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 26: Global: Die Attach Machine (Logic) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 27: Global: Die Attach Machine (Logic) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 28: Global: Die Attach Machine (Memory) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 29: Global: Die Attach Machine (Memory) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 30: Global: Die Attach Machine (CMOS Image Sensors) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 31: Global: Die Attach Machine (CMOS Image Sensors) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 32: Global: Die Attach Machine (LED) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 33: Global: Die Attach Machine (LED) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 34: Global: Die Attach Machine (Other Applications) Market: Sales Value (in Million US\$), 2018 & 2023

Figure 35: Global: Die Attach Machine (Other Applications) Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 36: North America: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 37: North America: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 38: United States: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 39: United States: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 40: Canada: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 41: Canada: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 42: Asia-Pacific: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 43: Asia-Pacific: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 44: China: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 45: China: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 46: Japan: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 47: Japan: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 48: India: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 49: India: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 50: South Korea: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 51: South Korea: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 52: Australia: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 53: Australia: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 54: Indonesia: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 55: Indonesia: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 56: Others: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 57: Others: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 58: Europe: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 59: Europe: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 60: Germany: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 61: Germany: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 62: France: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 63: France: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 64: United Kingdom: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 65: United Kingdom: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 66: Italy: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 67: Italy: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 68: Spain: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 69: Spain: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 70: Russia: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 71: Russia: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 72: Others: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 73: Others: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 74: Latin America: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 75: Latin America: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 76: Brazil: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 77: Brazil: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 78: Mexico: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 79: Mexico: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 80: Others: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 81: Others: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 82: Middle East and Africa: Die Attach Machine Market: Sales Value (in Million US\$), 2018 & 2023

Figure 83: Middle East and Africa: Die Attach Machine Market: Breakup by Country (in %), 2023

Figure 84: Middle East and Africa: Die Attach Machine Market Forecast: Sales Value (in Million US\$), 2024-2032

Figure 85: Global: Die Attach Machine Industry: Drivers, Restraints, and Opportunities

Figure 86: Global: Die Attach Machine Industry: Value Chain Analysis

Figure 87: Global: Die Attach Machine Industry: Porter's Five Forces Analysis

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